

RELIABILITY REPORT
FOR
MAX20323_ENC+T
WAFER LEVEL DEVICES

October 15, 2017

MAXIM INTEGRATED

160 RIO ROBLES
SAN JOSE, CA 95134

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Conclusion

The MAX20323_ENC+T successfully meets the quality and reliability standards required of all Maxim Integrated products. In addition, Maxim Integrated's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim Integrated's quality and reliability standards.

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I. Device Description

A. General

The MAX20323/MAX20323A/MAX20323B/MAX20323C/ MAX20323D/MAX20323E/MAX20323F overvoltage protectors feature internal overvoltage threshold and surge protection to turn off the switches and prevent damage to USB type-C CC/SBU pins. The devices have two channel switches with 0.27 Ω (typ) on-resistance that are turned on when inputs are below overvoltage threshold. When overvoltage threshold is exceeded on one of the channels, the corresponding switch is turned off and replaced by an accurate pullup current to output (CC1_O/CC2_O) that is sourced from input (CC1_I/CC2_I). (The MAX20323A/C/F do not have pullup current feature). The devices are available in a 12-bump (0.4mm pitch, 1.7mm x 1.32mm) WLP package and operate over the -40°C to +85°C extended temperature range.

II. Manufacturing Information

A. Description/Function:	USB Type-C CC-Pin Overvoltage Protector
B. Process:	S18
C. Number of Device Transistors:	8903
D. Fabrication Location:	USA
E. Assembly Location:	Taiwan
F. Date of Initial Production:	July 7, 2017

III. Packaging Information

A. Package Type:	12-bump thin WLP
B. Lead Frame:	N/A
C. Lead Finish:	N/A
D. Die Attach:	None
E. Bondwire:	N/A (N/A mil dia.)
F. Mold Material:	None
G. Assembly Diagram:	#05-100632
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Ja:	N/A°C/W
K. Single Layer Theta Jc:	N/A°C/W
L. Multi Layer Theta Ja:	72.82°C/W
M. Multi Layer Theta Jc:	N/A°C/W

IV. Die Information

A. Dimensions:	68.1102X53.1496 mils
B. Passivation:	Si ₃ N ₄ /SiO ₂ (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al/0.5%Cu with Ti/TiN Barrier
D. Minimum Metal Width:	0.23 microns (as drawn)
E. Minimum Metal Spacing:	0.23 microns (as drawn)
F. Isolation Dielectric:	SiO ₂
G. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

- A. Quality Assurance Contacts: Eric Wright (Reliability Engineering)
Brian Standley (Manager, Reliability)
Bryan Preeshl (Vice President of QA)
- B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.
0.1% for all Visual Defects.
- C. Observed Outgoing Defect Rate: < 50 ppm
- D. Sampling Plan: Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135C biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4340 \times 80 \times 2} \quad (\text{Chi square value for MTTF upper limit})$$

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$$\lambda = 13.7 \times 10^{-9}$$

$$\lambda = 13.7 \text{ F.I.T. (60\% confidence level @ 25°C)}$$

The following failure rate represents data collected from Maxim Integrated's reliability monitor program. Maxim Integrated performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at <http://www.maximintegrated.com/qa/reliability/monitor>. Cumulative monitor data for the S18 Process results in a FIT Rate of 0.40 @ 25C and 6.96 @ 55C (0.8 eV, 60% UCL)

B. E.S.D. and Latch-Up Testing

The AO10 die type has been found to have all pins able to withstand an HBM transient pulse of +/-2500V per JEDEC JESD22-A114. Latch-Up testing has shown that this device withstands a current of +/-250mA and overvoltage per JEDEC JESD78.

Table 1
Reliability Evaluation Test Results

MAX20323_ENC+T

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES	COMMENTS
Static Life Test (Note 1)	Ta = 135C Biased Time = 192 hrs.	DC Parameters & functionality	80	0	

Note 1: Life Test Data may represent plastic DIP qualification lots.